

Nonwoven fabric for printed wiring board and insulated board - contains specific amount of main body fiber and filler with another specific amount of thermosetting or inorganic binder resin for main body fiber and thermoplastic binder resin for filler

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Patent Details:

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Abstract (Basic): JP 11269752 A

NOVELTY - The nonwoven fabric contains 5-80 weight% of main body fiber A and 20-95 wt. % of filler D. The amount of thermosetting binder resin or inorganic binder resin B for the amount of main body fiber A is 3-20 wt. %. The amount of thermoplastic binder resin C for the amount of filler D is 3-20 wt. %. DETAILED DESCRIPTION - The main body fiber A having melting point, working point minimum temperature or decomposition point of 260 deg. C or more is bonded to thermosetting binder resin or inorganic binder resin B by dispersion. The thermoplastic binder resin C having melting point below 130 deg. C is bonded to the filler D. The composition of nonwoven fabric comprises 5-80 weight% of main body fiber A and 20-95 wt. % of filler D. The amount of thermosetting binder resin or inorganic binder resin B for the amount of main body fiber A is 3-20 wt. %. The amount of thermoplastic binder resin C for the amount of filler D is 3-20 wt. %.

USE - The nonwoven fabric is used for laminated sheet, such as printed wiring board and insulated board.

ADVANTAGE - When the nonwoven fabric is made into the laminated sheet, the sheet has high through hole dependability and low coefficient of thermal expansion with smooth surface. The interlaminar peeling does not occur in the laminated sheet.

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Title Terms: NONWOVEN; FABRIC; PRINT; WIRE; BOARD; INSULATE; BOARD; CONTAIN ; SPECIFIC; AMOUNT; MAIN; BODY; FILL; SPECIFIC; AMOUNT; THERMOSETTING; INORGANIC; BIND; RESIN; MAIN; BODY; THERMOPLASTIC; BIND; RESIN; FILL

Derwent Class: A85; F04; L03; V04; X12

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